

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5856624

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	SECURITY INTEREST

**CONVEYING PARTY DATA**

Name	Execution Date
AMBATURE, INC.	02/10/2016

**RECEIVING PARTY DATA**

<b>Name:</b>	AHRE INVESTMENTS, LLC ET AL.
<b>Street Address:</b>	1635 N. GREENFIELD RD #115
<b>City:</b>	MESA
<b>State/Country:</b>	ARIZONA
<b>Postal Code:</b>	85205

**PROPERTY NUMBERS Total: 27**

Property Type	Number
Application Number:	62360920
Application Number:	16576432
Application Number:	15644753
Application Number:	61583855
Application Number:	62222188
Application Number:	14195392
Application Number:	13832051
Application Number:	13076188
Application Number:	16680606
Application Number:	16680592
Application Number:	16680579
Application Number:	16407160
Application Number:	14008932
Application Number:	15167556
Application Number:	14169351
Application Number:	12896876
Application Number:	12896874
Application Number:	16528281
Application Number:	15167535
Application Number:	14105212

PATENT

Property Type	Number
Application Number:	12896873
Application Number:	14194226
Application Number:	12896870
Application Number:	14450308
Application Number:	13495523
Application Number:	12794688
PCT Number:	US2017041272

**CORRESPONDENCE DATA**

**Fax Number:**

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

**Phone:** 7034729954

**Email:** rick@toeringpatents.com

**Correspondent Name:** RICK A. TOERING

**Address Line 1:** PO BOX 1419

**Address Line 4:** LEESBURG, VIRGINIA 20177

**ATTORNEY DOCKET NUMBER:** A257 0000.0

**NAME OF SUBMITTER:** RICK A. TOERING

**SIGNATURE:** / rick a toering /

**DATE SIGNED:** 12/09/2019

**Total Attachments: 67**

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AMBATURE, INC.

SECURITY AGREEMENT

This Security Agreement (the "*Agreement*") is made as of February 10, 2016, by and between Ambature, Inc., a Delaware corporation (the "*Debtor*"), in favor of each of the parties listed on Exhibit A hereto (each a "*Secured Party*" and collectively the "*Secured Parties*").

RECITALS

The Secured Parties are the holders of those certain promissory notes as set forth on Exhibit A attached hereto (the "*Secured Notes*"). The parties intend that the Debtor's obligations to repay such Secured Notes be secured by the Collateral (as defined below) of the Debtor.

AGREEMENT

In consideration of the purchase of the Secured Notes by the Secured Parties and for other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the Debtor hereby agrees with the Secured Parties as follows:

**1. Grant of Security Interest; Right to Perfect.**

(a) **Grant of Security Interest.** To secure the Debtor's full and timely performance of all of the Debtor's obligations and liabilities to the Secured Parties pursuant to the Secured Notes (including, without limitation, any and all future advances made under the Secured Notes and Debtor's obligation to timely pay the principal amount of, and interest on, the Secured Notes) (the "*Obligations*"), the Debtor hereby grants to the Secured Parties a continuing security interest (the "*Security Interest*") in and to (i) all of the property and Debtor's interest in and to the property described on Exhibit B to this Agreement and (ii) all patents and patent intellectual property owned or held by Debtor from and after the date of this Agreement, (iii) all reissues, continuations, divisions or extensions of the foregoing, and (iv) all products and proceeds of the foregoing, including, without limitation, license royalties and proceeds of infringement suits, the right to sue for past, present and future infringements, all rights corresponding thereto throughout the world (the "*Collateral*"). The Security Interest shall be a first and prior interest in all of the Collateral.

(b) To perfect Secured Parties' Security Interest in the Collateral, Debtor hereby:

(i) Authorizes and consents to the filing of any and all UCC filings and any financing or continuation statements under the Uniform Commercial Code in any jurisdiction as may be required under the Uniform Commercial Code with respect to the liens created hereby; and

(ii) Authorizes, consents to and agrees to execute, if necessary, any and all filings and other documentation required to evidence Secured Parties' Security Interest in the records of the United States Patent and Trademark Office.

**2. Agreement Among the Secured Parties.**

(a) **Sharing of Collateral.** For purposes of this Agreement, "*Event of Default*" means any Default (as defined in the Secured Notes). Upon the occurrence and during the continuance of any Event of Default, and if the Secured Parties proceed to exercise any rights with respect to the Collateral, then, subject to Section 6 below, the Secured Parties shall share the Collateral and the proceeds of such Collateral ratably, without priority of one over the other, until the Obligations have been paid in full.

(b) **Appointment of Agent.** The Secured Parties agree that the Secured Parties holding at least a majority of the aggregate principal amount of the Secured Notes then outstanding (the "*Requisite Holders*") may act together as the agent of all Secured Parties to execute and deliver in their names such instruments, documents, statements and amendments thereto as may be necessary or appropriate to perfect or continue the perfection of the security interest granted in this Agreement.

(c) **Enforcement.** Enforcement of the Secured Parties' rights hereunder shall be taken by the Requisite Holders acting together as the agent for all of the Secured Parties. The action of such Requisite Holders taken in accordance with the preceding sentence shall in each case bind all the Secured Parties. Each of the Secured Parties agrees that any Secured Parties acting under Sections 2(b) and 2(c) shall not be liable for any acts taken in good faith in enforcing the rights of the Secured Parties hereunder.

**3. Covenants.** The Debtor covenants and agrees with the Secured Parties that, from and after the date of this Agreement until the Obligations are paid in full:

(a) **Other Liens.** Except for the Security Interest, the Debtor is the owner of the Collateral and will be the owner of the Collateral hereafter acquired free from any adverse lien, security interest or encumbrance (other than purchase money security interests that will be discharged upon Debtor's payment of the purchase price for the applicable property), and the Debtor will defend the Collateral against the claims and demands of all persons at any time claiming the same or any interest therein. No financing statements covering any Collateral or any proceeds thereof are on file in any public office.

(b) **Further Documentation.** At any time and from time to time, upon the written request of the Requisite Holders, and at the sole expense of the Debtor, the Debtor will promptly and duly execute and deliver such further instruments and documents and take such further action as the Requisite Holders may reasonably request for the purpose of obtaining or preserving the full benefits of this Agreement and of the rights and powers herein granted, including, without limitation, filing any financing or continuation statements under the Uniform Commercial Code in effect in any jurisdiction with respect to the liens created hereby and/or filing any documentation under the United States Patent and Trademark Office. The Debtor also hereby authorizes the Secured Parties to file any such financing or continuation statement

without the signature of the Debtor to the extent permitted by applicable law. A reproduction of this Agreement shall be sufficient as a financing statement (or as an exhibit to a financing statement on form UCC-1 for filing in any jurisdiction).

(c) **Indemnification.** The Debtor agrees to defend, indemnify and hold harmless the Secured Parties against any and all liabilities, costs and expenses (including, without limitation, legal fees and expenses): (i) with respect to, or resulting from, any delay in paying any and all excise, sales or other taxes which may be payable or determined to be payable with respect to any of the Collateral, (ii) with respect to, or resulting from, any delay in complying with any law, rule, regulation or order of any governmental authority applicable to any of the Collateral, or (iii) in connection with any of the transactions contemplated by this Agreement.

(d) **Maintenance of Records.** The Debtor will keep and maintain at its own cost and expense satisfactory and complete records of the Collateral.

(e) **Inspection Rights.** The Secured Parties shall have full access during normal business hours, and upon reasonable prior notice, to all the books, correspondence and other records of the Debtor relating to the Collateral, and the Secured Parties or their representatives may examine such records and make photocopies or otherwise take extracts from such records. The Debtor agrees to render to the Secured Parties, at the Debtor's expense, such clerical and other assistance as may be reasonably requested with regard to the exercise of its rights pursuant to this paragraph.

(f) **Compliance with Laws, etc.** The Debtor will comply in all material respects with all laws, rules, regulations and orders of any governmental authority applicable to any part of the Collateral or to the operation of the Debtor's business; provided, however, that the Debtor may contest any such law, rule, regulation or order in any reasonable manner which does not, in the reasonable opinion of the Debtor, adversely affect the Secured Parties' rights or the priority of their liens on the Collateral.

(g) **Payment of Obligations.** The Debtor will pay promptly when due all taxes, assessments and governmental charges or levies imposed upon the Collateral or with respect to any of its income or profits derived from the Collateral, as well as all claims of any kind (including, without limitation, claims for labor, materials and supplies) against or with respect to the Collateral, except that no such charge need be paid if (i) the validity of such charge is being contested in good faith by appropriate proceedings, (ii) such proceedings do not involve any material danger of the sale, forfeiture or loss of any of the Collateral or any interest in the Collateral, and (iii) such charge is adequately reserved against on the Debtor's books in accordance with generally accepted accounting principles.

(h) **Limitation on Liens on Collateral.** The Debtor will not create, incur or permit to exist, will defend the Collateral against, and will take such other action as is necessary to remove, any lien or claim on or to the Collateral, and will defend the right, title and interest of the Debtor and the Security Interest of the Secured Parties in and to any of the Collateral against the claims and demands of all other persons.

(i) **Limitations on Dispositions of Collateral.** The Debtor will not sell, transfer, lease or otherwise dispose of any of the Collateral, or attempt, offer or contract to do so, provided, however, that the Debtor will be allowed to (i) grant licenses to its products and related documentation in the ordinary course of business (ii) establish or provide for escrows of related intellectual property in connection therewith and (iii) grant one or more licenses (which may be exclusive or non-exclusive) to rights to the Company's intellectual property, technology, software and platform (and any related assets) for any markets outside of the United States in any transaction approved by the Debtor's Board of Directors (an "*International License*"). The Secured Parties shall not have any security interest in any International License, and shall execute any documents and take any actions reasonably requested by the Debtor in connection with evidencing the release of the applicable security interest in connection with any International License.

(j) **Further Identification of Collateral.** The Debtor will furnish to the Secured Parties from time to time statements and schedules further identifying and describing the Collateral and such other reports in connection with the Collateral as the Secured Parties may reasonably request, all in reasonable detail.

**4. Secured Parties' Appointment as Attorney-in-Fact.**

(a) **Powers.** The Debtor hereby appoints the Secured Parties, acting together through the Requisite Holders pursuant to the terms of this Agreement, and any officer or agent designated by the Requisite Holders, with full power of substitution, as its attorney-in-fact with full irrevocable power and authority in the place of the Debtor and in the name of the Debtor or in their own name, from time to time in the discretion of the Requisite Holders so long as an Event of Default has occurred and is continuing, for the purpose of carrying out the terms of this Agreement, to take any and all appropriate action and to execute any instrument which may be necessary or desirable to accomplish the purposes of this Agreement. Without limiting the foregoing, so long as an Event of Default has occurred and is continuing, the Requisite Holders shall have the right, without notice to, or the consent of, the Debtor, to do any of the following on the Debtor's behalf:

(i) to pay or discharge any taxes or liens levied or placed on or threatened against the Collateral;

(ii) to direct any party liable for any payment under any of the Collateral to make payment of any and all amounts due or to become due thereunder directly to the Secured Parties or as the Secured Parties direct;

(iii) to ask for or demand, collect, and receive payment of and receipt for, any payments due or to become due at any time in respect of or arising out of any Collateral;

(iv) to commence and prosecute any suits, actions or proceedings at law or in equity in any court of competent jurisdiction to enforce any right in respect of any Collateral;

(v) to defend any suit, action or proceeding brought against the Debtor with respect to any Collateral;

(vi) to settle, compromise or adjust any suit, action or proceeding described in subsection (v) above and to give such discharges or releases in connection therewith as the Secured Parties may deem appropriate;

(vii) subject to any International License, to assign any patent right included in the Collateral of Debtor (along with the goodwill of the business to which any such patent right pertains), throughout the world for such term or terms, on such conditions, and in such manner, as the Secured Parties shall in their sole discretion determine; and

(viii) generally, to sell, transfer, pledge and make any agreement with respect to or otherwise deal with any of the Collateral, and to take, at the Secured Parties' option and the Debtor's expense, any actions which the Secured Parties deem necessary to protect, preserve or realize upon the Collateral and the Secured Parties' liens on the Collateral and to carry out the intent of this Agreement, in each case to the same extent as if the Secured Parties were the absolute owner of the Collateral for all purposes.

The Debtor hereby ratifies whatever actions the Requisite Holders shall lawfully do or cause to be done in accordance with this Section 4. This power of attorney shall be a power coupled with an interest and shall be irrevocable.

**(b) No Duty on Secured Parties' Part.** The powers conferred on the Secured Parties by this Section 4 are solely to protect the Secured Parties' interests in the Collateral and shall not impose any duty upon them to exercise any such powers. Each Secured Party shall be accountable only for amounts that it actually receives as a result of the exercise of such powers, and neither the Secured Parties nor any of their officers, directors, employees or agents shall, in the absence of willful misconduct or gross negligence, be responsible to the Debtor for any act or failure to act pursuant to this Section 4.

**5. Performance by Secured Parties of Debtor's Obligations.** If the Debtor fails to perform or comply with any of its agreements or covenants contained in this Agreement and the Secured Parties perform or comply, or otherwise cause performance or compliance, with such agreement or covenant in accordance with the terms of this Agreement, then the reasonable expenses of the Secured Parties incurred in connection with such performance or compliance shall be payable by the Debtor to the Secured Parties on demand and shall constitute Obligations secured by this Agreement.

**6. Remedies.** If an Event of Default has occurred and is continuing, the Requisite Holders, on behalf of the Secured Parties, may exercise, in addition to all other rights and remedies granted to them in this Agreement and in any other instrument or agreement relating to the Obligations, all rights and remedies of a secured party under the Delaware Uniform Commercial Code, as amended from time to time (the "Code"). Without limiting the foregoing, the Requisite Holders, on behalf of the Secured Parties, without demand of performance or other



demand, presentment, protest, advertisement or notice of any kind (except any notice required by the Code or other law) to or upon the Debtor or any other person (all of which demands, defenses, advertisements and notices are hereby waived), may in such circumstances collect, receive, appropriate and realize upon any or all of the Collateral, and/or may sell, lease, assign, give option or options to purchase, or otherwise dispose of and deliver any or all of the Collateral (or contract to do any of the foregoing), in one or more parcels at public or private sale or sales, at any exchange, broker's board or office of a Secured Party or elsewhere upon such terms and conditions as are in accordance with the Code and as the Requisite Holders may otherwise deem advisable, for cash or on credit or for future delivery without assumption of any credit risk. The Secured Parties shall have the right upon any such public sale or sales, and, to the extent permitted by the Code or other law, upon any such private sale or sales, to purchase all or any part of the Collateral so sold, free of any right or equity of redemption in the Debtor, which right or equity is hereby waived or released. The Secured Parties shall apply the net proceeds of any such collection, recovery, receipt, appropriation, realization or sale, after deducting all reasonable expenses incurred therein or in connection with the care or safekeeping of any of the Collateral or in any way relating to the Collateral or the rights of the Secured Parties under this Agreement (including, without limitation, reasonable attorneys' fees and expenses) to the payment in whole or in part of the Obligations, in such order as the Secured Parties may elect, and only after such application and after the payment by the Secured Parties of any other amount required by any provision of law, need the Secured Parties account for the surplus, if any, to the Debtor. To the extent permitted by applicable law, the Debtor waives all claims, damages and demands it may acquire against the Secured Parties arising out of the exercise by the Secured Parties of any of their rights hereunder. If any notice of a proposed sale or other disposition of Collateral shall be required by law, such notice shall be deemed reasonable and proper if given at least twenty (20) days before such sale or other disposition. The Debtor shall remain liable for any deficiency if the proceeds of any sale or other disposition of the Collateral are insufficient to pay the Obligations and the fees and disbursements of any attorneys employed by the Secured Parties to collect such deficiency.

7. **Limitation on Duties Regarding Preservation of Collateral.** The sole duty of a Secured Party with respect to the custody, safekeeping and preservation of the Collateral, under Section 9207 of the Code or otherwise, shall be to deal with it in the same manner as such Secured Party deals with similar property for its own account. Neither the Secured Parties nor any of their directors, officers, employees or agents shall be liable for failure to demand, collect or realize upon all or any part of the Collateral or for any delay in doing so or shall be under any obligation to sell or otherwise dispose of any Collateral upon the request of the Debtor or otherwise.

8. **Powers Coupled with an Interest.** All authorizations and agencies contained in this Agreement with respect the Collateral are irrevocable and powers coupled with an interest.

9. **No Waiver; Cumulative Remedies.** The Secured Parties shall not by any act (except by a written instrument pursuant to Section 10(a) hereof), delay, indulgence, omission or otherwise be deemed to have waived any right or remedy hereunder or to have acquiesced in any default under the Secured Notes or in any breach of any of the terms and conditions of this Agreement. No failure to exercise, nor any delay in exercising, on the part of the Secured Parties, any right, power or privilege hereunder shall operate as a waiver thereof. No single or

partial exercise of any right, power or privilege hereunder shall preclude any other or further exercise thereof or the exercise of any other right, power or privilege. A waiver by the Secured Parties of any right or remedy under this Agreement on any one occasion shall not be construed as a bar to any right or remedy which the Secured Parties would otherwise have on any subsequent occasion. Each right, power and remedy of the Secured Parties provided for herein or in the Secured Notes, or now or hereafter existing at law or in equity shall be cumulative and concurrent, and the exercise by the Secured Parties of any one or more of the rights, powers or remedies provided for in this Agreement or the Secured Notes, or now or hereafter existing at law or in equity, shall not preclude the simultaneous or later exercise by any person, including the Secured Parties, of any or all other rights, powers or remedies.

**10. Miscellaneous.**

(a) **Amendments and Waivers.** Any term of this Agreement may be amended with the written consent of the Debtor and the Requisite Holders. Notwithstanding the foregoing or any other provision of this Agreement, no amendment or waiver that adversely affects a Secured Party in a manner different from all of the Secured Parties in their capacities as Secured Parties and the holders of Secured Notes or the Security Interest hereunder, may be effected without the written consent of such Secured Party. Any amendment or waiver effected in accordance with this Section 10(a) shall be binding upon the parties and their respective successors and assigns. Notwithstanding the foregoing, this Agreement may be amended for the purpose of adding additional purchasers of Secured Notes, in substantially the form of the Notes purchased by the other Secured Parties, as parties to this Agreement as "Secured Parties" by the execution and delivery of a counterpart signature page to this Agreement by such additional purchasers. In such event, Exhibit A shall be updated by the Debtor to reflect such additional Secured Parties without any other action by the other parties hereto.

(b) **Transfer; Successors and Assigns.** The terms and conditions of this Agreement shall be binding upon the Debtor and its successors and assigns and inure to the benefit of each Secured Party and its successors and assigns. Nothing in this Agreement, express or implied, is intended to confer upon any party other than the parties hereto or their respective successors and assigns any rights, remedies, obligations, or liabilities under or by reason of this Agreement, except as expressly provided in this Agreement.

(c) **Governing Law.** This Agreement and all acts and transactions pursuant hereto and the rights and obligations of the parties hereto shall be governed, construed and interpreted in accordance with the laws of the State of Delaware, without giving effect to principles of conflicts of law.

(d) **Counterparts.** This Agreement may be executed in two or more counterparts, each of which shall be deemed an original and all of which together shall constitute one instrument.

(e) **Titles and Subtitles.** The titles and subtitles used in this Agreement are used for convenience only and are not to be considered in construing or interpreting this Agreement.

(f) **Notices.** Any notice required or permitted by this Agreement shall be in writing and shall be deemed sufficient upon receipt, when delivered personally or by courier, overnight delivery service or confirmed facsimile, or forty-eight (48) hours after being deposited in the U.S. mail as certified or registered mail with postage prepaid, if such notice is addressed to the party to be notified at such party's address or facsimile number as set forth below or on Exhibit A hereto, or as subsequently modified by written notice.

(g) **Severability.** If one or more provisions of this Agreement are held to be unenforceable under applicable law, the parties agree to renegotiate such provision in good faith in order to maintain the economic position enjoyed by each party as close as possible to that under the provision rendered unenforceable. In the event that the parties cannot reach a mutually agreeable and enforceable replacement for such provision, then (i) such provision shall be excluded from this Agreement, (ii) the balance of the Agreement shall be interpreted as if such provision were so excluded, and (iii) the balance of the Agreement shall be enforceable in accordance with its terms.

(h) **Entire Agreement.** This Agreement, and the documents referred to herein constitute the entire agreement between the parties hereto pertaining to the subject matter hereof, and any and all other written or oral agreements existing between the parties hereto concerning such subject matter are expressly canceled.

11. **Extension of Maturity Dates.** The Holder (as defined in each of the Secured Notes), by executing this Agreement in the space provided below, hereby agrees to extend the maturity date of its Secured Note to September 30, 2016. Debtor and each Holder of a Secured Note hereby agree that, except for the extension of the maturity date of each Secured Note and the future advances made or to be made under any such Secured Note, each Secured Note shall remain unmodified and in full force and effect.

[Signature Page Follows]

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**GRANTOR:**

AMBATURE, INC.

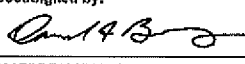
By: *R. J. Kelley*  
Ronald Kelly, Chief Executive Officer

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

AHRE Investments LLC

By: DocuSigned by:  
  
708EDDF131544DA ..

Name: David F Berg  
(print)

Title: Member

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Amster Family Trust

By: David M. Amster

Name: DAVID M. AMSTER

Title: Trustee (print)

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

DPP Group LLC

By:  \_\_\_\_\_

Name: PRYAM PAIL  
(print)

Title: \_\_\_\_\_

Signature Page to Security Agreement

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IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Davidson Family Trust

By: *Byron Davidson*

Name: BYRON DAVIDSON  
(print)

Title: Trustee

Signature Page to Security Agreement



IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Diamond Paradise Trust II

By: Michele Barnhill  
Name: Michele Barnhill  
(print)  
Title: Director

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Emerald Paradise Trust II

By: Ashley Barnhill

Name: Ashley Barnhill  
(print)

Title: Director

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Geeta Patel Living Trust

By: Geeta C. Patel

Name: GEETA PATEL  
(print)

Title: TRUSTEE

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Golden Paradise Investments LP

By: 

Name: Bruce Barnhill  
(print)

Title: Director

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

By:  \_\_\_\_\_

Name: Marc Kates

Title: \_\_\_\_\_

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Kismet Family Ltd.

By: 

Name: HEMANT PATEL  
(print)

Title: TRUSTEE

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Langer Investments LLC

By: W.A. Langer  
Name: W.A. LANGER JR  
(print)  
Title: MANAGER

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

By: S. N. Naye

Name: Sandeep Naye

Title: TRUSTEE

(NAYEE - NAIK FAMILY TRUST

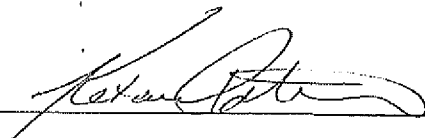
U/T/A DATED 10/29/07

Signature Page to Security Agreement



IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

By:  \_\_\_\_\_

Name: Ketan Patel

Title: ~~Resample~~ None \_\_\_\_\_

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Sanbud Properties Limited Partnership

By: Byron Davidson

Name: BYRON DAVIDSON  
(print)

Title: MEM

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

By: David Smith

Name: David Smith

Title: \_\_\_\_\_

By: Cassandra Smith

Name: Cassandra Smith

Title: \_\_\_\_\_

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

By: 

Name: Nick Thakore

Title: \_\_\_\_\_

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

By: George Weisz

Name: George Weisz

Title: \_\_\_\_\_

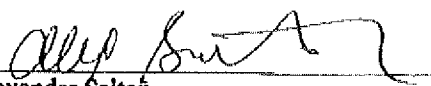
Signature Page to Security Agreement

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**PATENT**  
**REEL: 051227 FRAME: 0069**

The Debtor and Secured Parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

  
Alexander Salton

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

By:           *R. J. Kelly*          

Name: Ronald J. Kelly

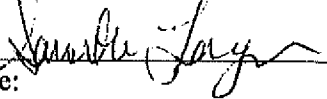
Title: \_\_\_\_\_

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Langer Energy Investments LLC

By:   
Name: \_\_\_\_\_

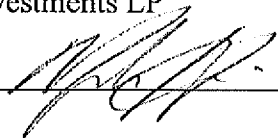
Signature Page to Security Agreement



IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

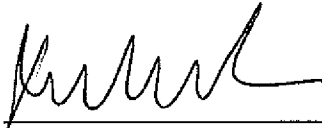
MYA Investments LP

By:   
Name: \_\_\_\_\_

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

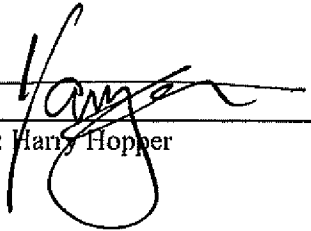
By: 

Name: M Giaketsis and L Bliss  
Family Trust dated May 9, 2016.

Trustee

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

By:   
Name: Harry Hopper

Signature Page to Security Agreement

PATENT  
REEL: 051227 FRAME: 0075

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Equity Trust Company  
Custodian FBO Andrew Spingler  
IRA

By: 

Name: **MATTHEW COLLIER**  
Corporate Alternate Signer

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

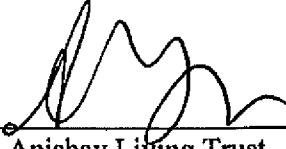
Equity Trust Company  
Custodian FBO Linda Spingler  
IRA

By: Matthew Collier

Name: **MATTHEW COLLIER**  
Corporate Alternate Signer

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:


By:   
Name: Anishay Living Trust

Signature Page to Security Agreement

PATENT  
REEL: 051227 FRAME: 0078

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

By:   
John Phillips as Trustee  
of Phillips Family Trust

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Strasser Revocable Trust

By: Michael D. Strasser  
Trustee: Michael Strasser

Signature Page to Security Agreement



IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

**SECURED PARTY:**

Duff Berquist & Maureen Berquist  
Joint Tenants

By:


A handwritten signature in cursive script, appearing to read "Duff Berquist", written over a horizontal line.

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Patel Chhaya Family Trust

By:   
Sandeep Patel

Signature Page to Security Agreement

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Bricker Revocable Trust

By: Robert Bricker  
Trustee: Robert Bricker

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

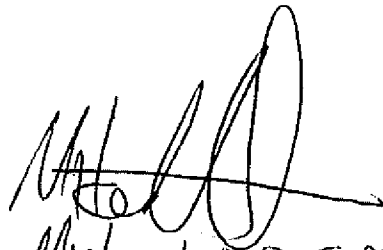
SECURED PARTY:

MICHAEL J. DESOTO &

KERI R. DESOTO

JOINT TENANTS

By:



Michael J Desoto 3-1-19




Keri Desoto 3/1/19

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Paul and Gail Wham  
Tenants in Common

By:   
Gail Wham

By:   
Paul Wham

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

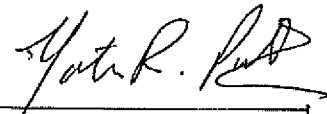
By:   
Enjian Lin

Signature Page to Security Agreement

**PATENT**  
**REEL: 051227 FRAME: 0086**

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

By:   
Yatin Patel

Signature Page to Security Agreement

**PATENT**  
**REEL: 051227 FRAME: 0087**

IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

Patel Revocable Inter-Vivos Trust

By: Ramona K. Patel  
Ramona K. Patel

Signature Page to Security Agreement

PATENT  
REEL: 051227 FRAME: 0088



IN WITNESS WHEREOF, the parties have caused this Security Agreement to be duly executed and delivered as of the date first above written.

SECURED PARTY:

By: Roshni Patel  
Roshni A. Patel

Signature Page to Security Agreement

**PATENT**  
**REEL: 051227 FRAME: 0089**

**EXHIBIT A**

**Schedule of Secured Parties**

**(As of December 31 , 2015)**

<b>Name of Purchaser</b>	<b>Principal Amount of Note, including Interest</b>	<b>Date of Note</b>
AHRE Investments LLC	\$60,000.00	
Amster Family Trust	\$7,000.00	
DPP Group LLC	\$101,086.00	
Davidson Family Trust	\$25,000.00	
Diamond Paradise Trust II	\$10,000.00	
Emerald Paradise Trust II	\$10,000.00	
Geeta Patel Living Trust	\$25,000.00	
Goiden Paradise Investments LP	\$60,000.00	
Marc Kates	\$10,000.00	
Kismet Family Ltd	\$50,000.00	
Langer Investments LLC	\$69,920.00	
Nishel Narotam	\$49,972.75	
Sandeep Nayee	\$30,000.00	
Ketan Patel	\$30,000.00	
Sanbud Properties	\$10,000.00	
David & Cassandra Smith	\$20,000.00	
Nick Thakore	\$150,000.00	
George Weisz	\$65,000.00	
Ronald J. Kelly	\$746,462.00	
<b>Total:</b>	<b>\$ 1,665,271.82</b>	

## EXHIBIT B

### Collateral

HIGH TEMPERATURE SUPERCONDUCTING MATERIALS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00001								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1010.P	US	Expired in favor of: AMB-00003 AMB-00005	61/248,134	10/02/2009				

HIGH TEMPERATURE EXTREMELY LOW RESISTANCE MATERIALS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00002								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1020.P	US	Expired in favor of: AMB-00006 AMB-00007	61/248,130	10/02/2009				

AN EXTREMELY LOW RESISTANCE COMPOSITION AND METHODS FOR CREATING SAME AMB-00004								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1030.1	US	Granted	12/794,688	06/04/2010	US-2011-0268918-A1	11/03/2011	8,211,833	07/03/2012
A257 1030.2	US	Granted	13/495,523	06/13/2012	US-2012-0258864-A1	10/11/2012	8,796,181	08/05/2014
A257 1030.3	US	Pending	14/450,308	08/04/2014	US-2015-0188020-A1	07/02/2015		

## EXHIBIT B

### Collateral (Continued)

EXTREMELY LOW RESISTANCE MATERIALS AND METHODS FOR MODIFYING AND CREATING SAME AMB-00003								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1040.1	US	Expired in favor of A257 1040.2	12/896,870	10/02/2010	US-2011-0082045-A1	04/07/2011		
A257 1040.2	US	Pending (Soon to grant)	14/194,226	02/28/2014	US 2014-0364319 A1	12/11/2014		
A257 1040TW	Taiwan	Published	099133794	10/04/2010	201130178	09/01/2011		

EXTREMELY LOW RESISTANCE FILMS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00005								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1050.1	US	Granted	12/896,873	10/02/2010	US-2011-0082042-A1	04/07/2011	8,609,593	12/17/2013
A257 1050.2	US	Pending (Soon to grant)	14/105,212	12/13/2013	US 2014-0336053 A1	11/13/2014		
A257 1050TW	Taiwan	Published	099133798	10/04/2010	201130179	09/01/2011		
A257 1050WO	WIPO/PCT	Expired	PCT/US2010/051239	10/02/2010	WO 2011/041764	04/07/2011		
A257 1050AU	Australia	Pending	2010300364	05/01/2012				
A257 1050CA	Canada	Published	2,779,609	05/01/2012	2779609	04/07/2011		
A257 1050CN	China	Published	201080054808.8	06/01/2012	CN102714216A 10/03/2012			
A257 1050EP	Europe	Published	10821387.7	05/01/2012	2483927 08/08/2012			
A257 1050HK	Hong Kong	Pending	13101847.8	02/08/2013				

**EXHIBIT B****Collateral  
(Continued)**

EXTREMELY LOW RESISTANCE FILMS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00005								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1050IL	Israel	Pending	218983	04/02/2012				
A257 1050IN	India	Pending	1070/KOLNP/2012	05/02/2012				
A257 1050JP	Japan	Published	2012-532382	04/02/2012	2013-507009	02/28/2013		
A257 1050KR	Korea	Pending	10-2012-7011475	05/02/2012				
A257 1050RU	Russia	Pending	2012118038	05/02/2012				

HIGH TEMPERATURE SUPERCONDUCTING MATERIALS AND METHODS FOR MODIFYING AND CREATING SAME AMB-00006								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1060.1	US	Pending	12/896,874	10/02/2010	US-2011-0082041-A1	04/07/2011		
A257 1060TW	Taiwan	Published	099133795	10/04/2010	201128826	10/16/2011		

**EXHIBIT B**

**Collateral  
(Continued)**

HIGH TEMPERATURE SUPERCONDUCTING FILMS AND METHODS FOR MODIFYING AND CREATING SAME AMB-00007								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1070.1	US	Granted	12/896,876	10/02/2010	US-2011-0082044-A1	04/07/2011	8,759,257	06/24/2014
A257 1070.2	US	Pending (Soon to grant)	14/169,351	01/31/2014	US 2014-0336054 A1	11/13/2014		
A257 1070TW	Taiwan	Published	099133793	10/04/2010	201135992	10/16/2011		

EXTREMELY LOW RESISTANCE COMPOSITIONS AND METHODS FOR CREATING SAME AMB-08000								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1490.1	US	Granted	13/076,188	03/30/2011	US-2012-0252676-A1	04/10/2012	8,404,620	03/26/2013
A257 1490.2	US	Expired in favor of A257 1490.3	13/832,051	03/15/2013	US-2013-0196858-A1	08/01/2013		
A257 1490.3	US	Pending (Soon to grant)	14/450,308	08/04/2014	US 2014-0329686 A1	11/06/2014		

**EXHIBIT B**

**Collateral  
(Continued)**

ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS AMB-00011								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1080WO	WO	Published	PCT/US2012/031554	03/30/2012	WO 2012/135683	10/04/2012		
Claims priority to 165 U.S. Provisional Applications that were filed on 03/30/2011								
A257 1080.1	US	Published	14/008,932	09/30/2013	US 2014-0113828 A1	04/24/2014		
A257 1080AU	Australia	Expired in favor of A257 1080AU.2	2012236227	10/28/2013				
A257 1080AU.2	Australia	Pending	2015275326	12/23/2015				
A257 1080CA	Canada	Pending	2,868,986	09/24/2014				
A257 1080CN	China	Pending	201280044226.0	11/29/2013				
A257 1080EP	Europe	Pending	12763184.4	10/25/2013				

**EXHIBIT B**

**Collateral  
(Continued)**

ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS AMB-00011								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1080IL	israel	Pending	228645	9/30/2013				
A257 1080IN	India	Pending	3193/KOLNP/2013	10/29/2013				
A257 1080JP	Japan	Pending	2014-502854	9/30/2013				
A257 1080KR	Korea	Pending	10-2013-7028718	10/30/2013				
A257 1080RU	Russia	Pending	2013148124	10/29/2013				

NOVEL YBCO PARTICULATES								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1500.P	US	Pending	62/222,188	09/22/2015				



**EXHIBIT B**

**Collateral  
(Continued)**

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
4 October 2012 (04.10.2012)

(10) International Publication Number  
**WO 2012/135683 A1**

(51) International Patent Classification:	61/469,605	30 March 2011 (30.03.2011)	US
<i>H01L 39/00</i> (2006.01)	61/469,641	30 March 2011 (30.03.2011)	US
(21) International Application Number:	61/469,673	30 March 2011 (30.03.2011)	US
	PCT/US2012/031554	61/469,675	30 March 2011 (30.03.2011)
(22) International Filing Date:	61/469,642	30 March 2011 (30.03.2011)	US
	30 March 2012 (30.03.2012)	61/469,678	30 March 2011 (30.03.2011)
(25) Filing Language:	English	61/469,591	30 March 2011 (30.03.2011)
(26) Publication Language:	English	61/469,608	30 March 2011 (30.03.2011)
(30) Priority Data:		61/469,619	30 March 2011 (30.03.2011)
	61/469,665	30 March 2011 (30.03.2011)	US
	61/469,313	30 March 2011 (30.03.2011)	US
	61/469,318	30 March 2011 (30.03.2011)	US
	61/469,756	30 March 2011 (30.03.2011)	US
	61/469,648	30 March 2011 (30.03.2011)	US
	61/469,293	30 March 2011 (30.03.2011)	US
	61/469,703	30 March 2011 (30.03.2011)	US
	61/469,621	30 March 2011 (30.03.2011)	US
	61/469,740	30 March 2011 (30.03.2011)	US
	61/469,617	30 March 2011 (30.03.2011)	US
	61/469,612	30 March 2011 (30.03.2011)	US
	61/469,637	30 March 2011 (30.03.2011)	US
	61/469,679	30 March 2011 (30.03.2011)	US
	61/469,283	30 March 2011 (30.03.2011)	US
	61/469,567	30 March 2011 (30.03.2011)	US
	61/469,571	30 March 2011 (30.03.2011)	US
	61/469,573	30 March 2011 (30.03.2011)	US
	61/469,576	30 March 2011 (30.03.2011)	US
	61/469,580	30 March 2011 (30.03.2011)	US
	61/469,584	30 March 2011 (30.03.2011)	US
	61/469,585	30 March 2011 (30.03.2011)	US

[Continued on next page]

(54) Title: ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS

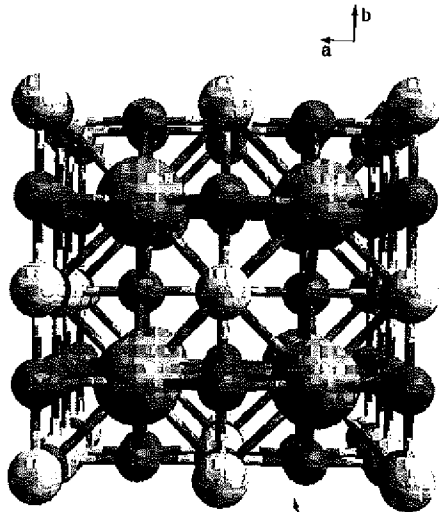


FIG. 1 100

(57) Abstract: Electrical, mechanical, computing, and/or other devices that include components formed of extremely low resistance (ELR) materials, including, but not limited to, modified ELR materials, layered ELR materials, and new ELR materials, are described.

WO 2012/135683 A1



## **EXHIBIT B**

### **Collateral (Continued)**

WO 2012/135683

PCT/US2012/031554

#### **ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS**

##### **CROSS-REFERENCE TO RELATED APPLICATIONS**

[0001] This application claims priority to: U.S. Provisional Patent Application Nos. 61/469,283, 61/469,567, 61/469,571, 61/469,573, and 61/469,576, entitled "Extremely Low Resistance Nanowires"; U.S. Provisional Patent Application Nos. 61/469,293, 61/469,580, 61/469,584, 61/469,585, 61/469,586, 61/469,589, 61/469,590, and 61/469,592, entitled "Inductors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,303, 61/469,591, 61/469,595, 61/469,600, 61/469,602, 61/469,605, 61/469,609, 61/469,613, 61/469,618, and 61/469,652 entitled "Capacitors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,313, 61/469,620, 61/469,622, 61/469,627, 61/469,630, 61/469,632, 61/469,635, 61/469,640, and 61/469,645 entitled "Transistors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,318, 61/469,599, 61/469,604, 61/469,608, 61/469,612, 61/469,617, 61/469,619, 61/469,624, and 61/469,628, entitled "Rotating Machines Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,324, 61/469,637, 61/469,641, and 61/469,644 entitled "Bearings Assemblies Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,331 and 61/469,650 entitled "Transformer Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,335, 61/469,656, 61/469,658, 61/469,659, and 61/469,662 entitled "Power Transmission Components Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,342, 61/469,667, 61/469,679, 61/469,684, and 61/469,769 entitled "Fault Current Limiter Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,358, 61/469,603, 61/469,606, 61/469,610, 61/469,615, 61/469,621, 61/469,625, 61/469,633, 61/469,639, 61/469,642, 61/469,653, 61/469,657, 61/469,665, and 61/469,668 entitled "MRI Components and Apparatus Employing Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,361, 61/469,623, 61/469,634, 61/469,643, and 61/469,648 entitled "Extremely Low Resistance Josephson Junctions"; U.S. Provisional Patent Application Nos. 61/469,363, 61/469,655, 61/469,660, 61/469,666, 61/469,671, 61/469,675, 61/469,678, 61/469,685, and

## **EXHIBIT B**

### **Collateral (Continued)**

WO 2012/135683

PCT/US2012/031554

61/469,691 entitled "Extremely Low Resistance Quantum Interference Devices"; U.S. Provisional Patent Application Nos. 61/469,367, 61/469,697, 61/469,700, 61/469,703, 61/469,704, and 61/469,710 entitled "Antennas Formed from Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,371, 61/469,717, 61/469,721, 61/469,727, 61/469,731, 61/469,735, 61/469,740, and 61/469,756 entitled "Filters Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,398, 61/469,654, 61/469,673, 61/469,683, 61/469,687, 61/469,692, 61/469,711, 61/469,716, 61/469,723, 61/469,638, 61/469,646, 61/469,728, 61/469,737, 61/469,743, 61/469,745, 61/469,751, 61/469,754, 61/469,761, 61/469,766, 61/469,770, 61/469,772, 61/469,774 and 61/469,775 entitled "Sensors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,401, 61/469,672, 61/469,674, 61/469,676, and 61/469,681 entitled "Actuators Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,376, 61/469,686, 61/469,690, 61/469,693, 61/469,694, 61/469,695, 61/469,696, and 61/469,698 entitled "Integrated Circuits Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,392, 61/469,707, 61/469,709, and 61/469,712 entitled "Extremely Low Resistance Interconnect (ELRI) For System in Package (SIP) Applications"; U.S. Provisional Patent Application Nos. 61/469,424, 61/469,714, 61/469,718, 61/469,720, 61/469,724, 61/469,726, and 61/469,730 entitled "Extremely Low Resistance Interconnect (ELRI) Connecting MEMS to Circuits on a Semiconductor IC"; U.S. Provisional Patent Application Nos. 61/469,387, 61/469,732, 61/469,736, and 61/469,739 entitled "Extremely Low Resistance Interconnect (ELRI) for RF Circuits on a Semiconductor Integrated Circuit"; U.S. Provisional Patent Application Nos. 61/469,554, 61/469,742, 61/469,744, 61/469,747, 61/469,749, and 61/469,750 entitled "Integrated Circuit Devices Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,560, 61/469,753, 61/469,755, 61/469,757, 61/469,758, 61/469,759, 61/469,760, 61/469,762, and 61/469,763 entitled "Energy Storage Devices Formed of Extremely Low Resistance Materials"; and U.S. Patent Application No. 13/076,188 entitled "Extremely Low Resistance Compositions and Methods for Creating Same." Each of the aforementioned applications was filed on March 30, 2011. Each of the aforementioned applications is incorporated herein by reference in its entirety.

**[0002]** This application also claims priority to U.S. Provisional Patent Application No. 61/583,855 entitled "Layered Compositions, Such as Compositions that Exhibit

**EXHIBIT B**

**Collateral**

HIGH TEMPERATURE SUPERCONDUCTING MATERIALS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00001								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1010.P	US	Expired in favor of: AMB-00003 AMB-00005	61/248,134	10/02/2009				

HIGH TEMPERATURE EXTREMELY LOW RESISTANCE MATERIALS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00002								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1020.P	US	Expired in favor of: AMB-00006 AMB-00007	61/248,130	10/02/2009				

AN EXTREMELY LOW RESISTANCE COMPOSITION AND METHODS FOR CREATING SAME AMB-00004								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1030.1	US	Granted	12/794,688	06/04/2010	US-2011-0268918-A1	11/03/2011	8,211,833	07/03/2012
A257 1030.2	US	Granted	13/495,523	06/13/2012	US-2012-0258864-A1	10/11/2012	8,796,181	08/05/2014
A257 1030.3	US	Pending	14/450,308	08/04/2014	US-2015-0188020-A1	07/02/2015		

**EXHIBIT B**

**Collateral  
(Continued)**

EXTREMELY LOW RESISTANCE MATERIALS AND METHODS FOR MODIFYING AND CREATING SAME AMB-00003								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1040.1	US	Expired in favor of A257 1040.2	12/896,870	10/02/2010	US-2011-0082045-A1	04/07/2011		
A257 1040.2	US	Pending (Soon to grant)	14/194,226	02/28/2014	US 2014-0364319 A1	12/11/2014		
A257 1040TW	Taiwan	Published	099133794	10/04/2010	201130178	09/01/2011		

EXTREMELY LOW RESISTANCE FILMS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00005								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1050.1	US	Granted	12/896,873	10/02/2010	US-2011-0082042-A1	04/07/2011	8,609,593	12/17/2013
A257 1050.2	US	Pending (Soon to grant)	14/105,212	12/13/2013	US 2014-0336053 A1	11/13/2014		
A257 1050TW	Taiwan	Published	099133798	10/04/2010	201130179	09/01/2011		
A257 1050WO	WIPO/PCT	Expired	PCT/US2010/051239	10/02/2010	WC 2011/041764	04/07/2011		
A257 1050AU	Australia	Pending	2010300364	05/01/2012				
A257 1050CA	Canada	Published	2,779,609	05/01/2012	2779609	04/07/2011		
A257 1050CN	China	Published	201080054808.8	06/01/2012	CN102714216A 10/03/2012			
A257 1050EP	Europe	Published	10821387.7	05/01/2012	2483927 08/08/2012			
A257 1050HK	Hong Kong	Pending	13101847.8	02/08/2013				

**EXHIBIT B****Collateral  
(Continued)**

EXTREMELY LOW RESISTANCE FILMS AND METHODS FOR MODIFYING OR CREATING SAME AMB-00005								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1050IL	Israel	Pending	218983	04/02/2012				
A257 1050IN	India	Pending	1070/KOLNP/2012	05/02/2012				
A257 1050JP	Japan	Published	2012-532382	04/02/2012	2013-507009	02/28/2013		
A257 1050KR	Korea	Pending	10-2012-7011475	05/02/2012				
A257 1050RU	Russia	Pending	2012118038	05/02/2012				

HIGH TEMPERATURE SUPERCONDUCTING MATERIALS AND METHODS FOR MODIFYING AND CREATING SAME AMB-00006								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1060.1	US	Pending	12/896,874	10/02/2010	US-2011-0082041-A1	04/07/2011		
A257 1060TW	Taiwan	Published	099133795	10/04/2010	201128826	10/16/2011		

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(Continued)**

HIGH TEMPERATURE SUPERCONDUCTING FILMS AND METHODS FOR MODIFYING AND CREATING SAME AMB-00007								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1070.1	US	Granted	12/896,876	10/02/2010	US-2011-0082044-A1	04/07/2011	8,759,257	06/24/2014
A257 1070.2	US	Pending (Soon to grant)	14/169,351	01/31/2014	US 2014-0336054 A1	11/13/2014		
A257 1070TW	Taiwan	Published	099133793	10/04/2010	201135992	10/16/2011		

EXTREMELY LOW RESISTANCE COMPOSITIONS AND METHODS FOR CREATING SAME AMB-08000								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1490.1	US	Granted	13/076,188	03/30/2011	US-2012-0252676-A1	04/10/2012	8,404,620	03/26/2013
A257 1490.2	US	Expired in favor of A257 1490.3	13/832,051	03/15/2013	US-2013-0196858-A1	08/01/2013		
A257 1490.3	US	Pending (Soon to grant)	14/450,308	08/04/2014	US 2014-0329686 A1	11/06/2014		



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ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS AMB-00011								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1080WO  Claims priority to 165 U.S. Provisional Applications that were filed on 03/30/2011	WO	Published	PCT/US2012/031554	03/30/2012	WO 2012/135683	10/04/2012		
A257 1080.1	US	Published	14/008,932	09/30/2013	US 2014-0113828 A1	04/24/2014		
A257 1080AU	Australia	Expired in favor of A257 1080AU.2	2012236227	10/28/2013				
A257 1080AU.2	Australia	Pending	2015275326	12/23/2015				
A257 1080CA	Canada	Pending	2,868,986	09/24/2014				
A257 1080CN	China	Pending	201280044226.0	11/29/2013				
A257 1080EP	Europe	Pending	12763184.4	10/25/2013				

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**Collateral  
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ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS AMB-00011								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1080IL	Israel	Pending	228645	9/30/2013				
A257 1080IN	India	Pending	3193/KOLNP/2013	10/29/2013				
A257 1080JP	Japan	Pending	2014-502854	9/30/2013				
A257 1080KR	Korea	Pending	10-2013-7028718	10/30/2013				
A257 1080RU	Russia	Pending	2013148124	10/29/2013				

NOVEL YBCO PARTICULATES								
Docket No.:	Country	Status	Application No.	Filing Date	Pub. No.	Pub. Date	Patent No.	Issue Date
A257 1500.P	US	Pending	62/222,188	09/22/2015				

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**Collateral  
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(10) International Publication Number  
**WO 2012/135683 A1**

(51) International Patent Classification:	61/469,605	30 March 2011 (30.03.2011)	US
<i>H01L 39/00</i> (2006.01)	61/469,641	30 March 2011 (30.03.2011)	US
(21) International Application Number:	61/469,673	30 March 2011 (30.03.2011)	US
	PCT/US2012/031554	61/469,675	30 March 2011 (30.03.2011)
(22) International Filing Date:	61/469,642	30 March 2011 (30.03.2011)	US
	30 March 2012 (30.03.2012)	61/469,678	30 March 2011 (30.03.2011)
(25) Filing Language:	English	61/469,591	30 March 2011 (30.03.2011)
(26) Publication Language:	English	61/469,608	30 March 2011 (30.03.2011)
(30) Priority Data:		61/469,619	30 March 2011 (30.03.2011)
	61/469,665	30 March 2011 (30.03.2011)	US
	61/469,313	30 March 2011 (30.03.2011)	US
	61/469,318	30 March 2011 (30.03.2011)	US
	61/469,756	30 March 2011 (30.03.2011)	US
	61/469,648	30 March 2011 (30.03.2011)	US
	61/469,293	30 March 2011 (30.03.2011)	US
	61/469,703	30 March 2011 (30.03.2011)	US
	61/469,621	30 March 2011 (30.03.2011)	US
	61/469,740	30 March 2011 (30.03.2011)	US
	61/469,617	30 March 2011 (30.03.2011)	US
	61/469,612	30 March 2011 (30.03.2011)	US
	61/469,637	30 March 2011 (30.03.2011)	US
	61/469,679	30 March 2011 (30.03.2011)	US
	61/469,283	30 March 2011 (30.03.2011)	US
	61/469,567	30 March 2011 (30.03.2011)	US
	61/469,571	30 March 2011 (30.03.2011)	US
	61/469,573	30 March 2011 (30.03.2011)	US
	61/469,576	30 March 2011 (30.03.2011)	US
	61/469,580	30 March 2011 (30.03.2011)	US
	61/469,584	30 March 2011 (30.03.2011)	US
	61/469,585	30 March 2011 (30.03.2011)	US

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(54) Title: ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS

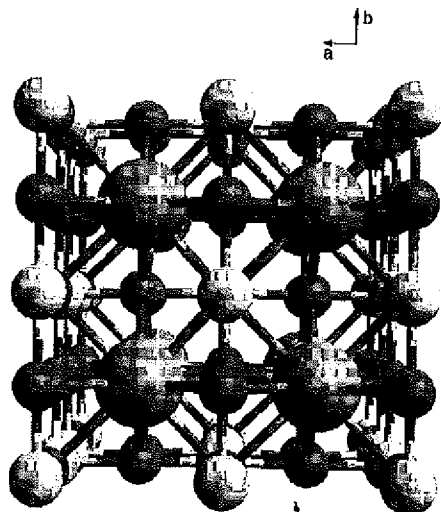


FIG. 1 100

(57) Abstract: Electrical, mechanical, computing, and/or other devices that include components formed of extremely low resistance (ELR) materials, including, but not limited to, modified ELR materials, layered ELR materials, and new ELR materials, are described.

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#### **ELECTRICAL, MECHANICAL, COMPUTING, AND/OR OTHER DEVICES FORMED OF EXTREMELY LOW RESISTANCE MATERIALS**

##### **CROSS-REFERENCE TO RELATED APPLICATIONS**

[0001] This application claims priority to: U.S. Provisional Patent Application Nos. 61/469,283, 61/469,567, 61/469,571, 61/469,573, and 61/469,576, entitled "Extremely Low Resistance Nanowires"; U.S. Provisional Patent Application Nos. 61/469,293, 61/469,580, 61/469,584, 61/469,585, 61/469,586, 61/469,589, 61/469,590, and 61/469,592, entitled "Inductors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,303, 61/469,591, 61/469,595, 61/469,600, 61/469,602, 61/469,605, 61/469,609, 61/469,613, 61/469,618, and 61/469,652 entitled "Capacitors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,313, 61/469,620, 61/469,622, 61/469,627, 61/469,630, 61/469,632, 61/469,635, 61/469,640, and 61/469,645 entitled "Transistors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,318, 61/469,599, 61/469,604, 61/469,608, 61/469,612, 61/469,617, 61/469,619, 61/469,624, and 61/469,628, entitled "Rotating Machines Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,324, 61/469,637, 61/469,641, and 61/469,644 entitled "Bearings Assemblies Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,331 and 61/469,650 entitled "Transformer Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,335, 61/469,656, 61/469,658, 61/469,659, and 61/469,662 entitled "Power Transmission Components Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,342, 61/469,667, 61/469,679, 61/469,684, and 61/469,769 entitled "Fault Current Limiter Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,358, 61/469,603, 61/469,606, 61/469,610, 61/469,615, 61/469,621, 61/469,625, 61/469,633, 61/469,639, 61/469,642, 61/469,653, 61/469,657, 61/469,665, and 61/469,668 entitled "MRI Components and Apparatus Employing Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,361, 61/469,623, 61/469,634, 61/469,643, and 61/469,648 entitled "Extremely Low Resistance Josephson Junctions"; U.S. Provisional Patent Application Nos. 61/469,363, 61/469,655, 61/469,660, 61/469,666, 61/469,671, 61/469,675, 61/469,678, 61/469,685, and

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61/469,691 entitled "Extremely Low Resistance Quantum Interference Devices"; U.S. Provisional Patent Application Nos. 61/469,367, 61/469,697, 61/469,700, 61/469,703, 61/469,704, and 61/469,710 entitled "Antennas Formed from Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,371, 61/469,717, 61/469,721, 61/469,727, 61/469,731, 61/469,735, 61/469,740, and 61/469,756 entitled "Filters Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,398, 61/469,654, 61/469,673, 61/469,683, 61/469,687, 61/469,692, 61/469,711, 61/469,716, 61/469,723, 61/469,638, 61/469,646, 61/469,728, 61/469,737, 61/469,743, 61/469,745, 61/469,751, 61/469,754, 61/469,761, 61/469,766, 61/469,770, 61/469,772, 61/469,774 and 61/469,775 entitled "Sensors Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,401, 61/469,672, 61/469,674, 61/469,676, and 61/469,681 entitled "Actuators Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,376, 61/469,686, 61/469,690, 61/469,693, 61/469,694, 61/469,695, 61/469,696, and 61/469,698 entitled "Integrated Circuits Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,392, 61/469,707, 61/469,709, and 61/469,712 entitled "Extremely Low Resistance Interconnect (ELRI) For System in Package (SIP) Applications"; U.S. Provisional Patent Application Nos. 61/469,424, 61/469,714, 61/469,718, 61/469,720, 61/469,724, 61/469,726, and 61/469,730 entitled "Extremely Low Resistance Interconnect (ELRI) Connecting MEMS to Circuits on a Semiconductor IC"; U.S. Provisional Patent Application Nos. 61/469,387, 61/469,732, 61/469,736, and 61/469,739 entitled "Extremely Low Resistance Interconnect (ELRI) for RF Circuits on a Semiconductor Integrated Circuit"; U.S. Provisional Patent Application Nos. 61/469,554, 61/469,742, 61/469,744, 61/469,747, 61/469,749, and 61/469,750 entitled "Integrated Circuit Devices Formed of Extremely Low Resistance Materials"; U.S. Provisional Patent Application Nos. 61/469,560, 61/469,753, 61/469,755, 61/469,757, 61/469,758, 61/469,759, 61/469,760, 61/469,762, and 61/469,763 entitled "Energy Storage Devices Formed of Extremely Low Resistance Materials"; and U.S. Patent Application No. 13/076,188 entitled "Extremely Low Resistance Compositions and Methods for Creating Same." Each of the aforementioned applications was filed on March 30, 2011. Each of the aforementioned applications is incorporated herein by reference in its entirety.

[0002] This application also claims priority to U.S. Provisional Patent Application No. 61/583,855 entitled "Layered Compositions, Such as Compositions that Exhibit